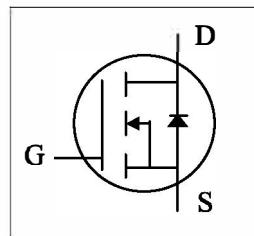
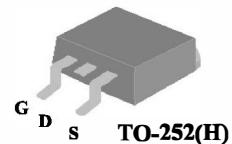


**AP10N10K****N-Channel Power MOSFET**

- ▼ 100%  $R_g$  & UIS Test
- ▼ Simple Drive Requirement
- ▼ Fast Switching Characteristic
- ▼ RoHS Compliant & Halogen-Free



$BV_{DSS}$	100V
$R_{DS(ON)}$	135mΩ
$I_D$	10A

**Description**

AP10N10K series are from Advanced Power innovative design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for use in a wide range of power applications.

The TO-252 package is widely preferred for all commercial-industrial surface mount applications using infrared reflow technique and suited for high current application due to the low connection resistance.

**Absolute Maximum Ratings@ $T_j=25^\circ\text{C}$ (unless otherwise specified)**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	+20	V
$I_D@T_c=25^\circ\text{C}$	Drain Current, $V_{GS} @ 10\text{V}$	8.1	A
$I_D@T_c=100^\circ\text{C}$	Drain Current, $V_{GS} @ 10\text{V}$	5.1	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	28	A
$P_D@T_c=25^\circ\text{C}$	Total Power Dissipation	20.8	W
$P_D@T_A=25^\circ\text{C}$	Total Power Dissipation <sup>3</sup>	2	W
$E_{AS}$	Single Pulse Avalanche Energy <sup>4</sup>	8	mJ
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Data**

Symbol	Parameter	Value	Units
$R_{thj-c}$	Maximum Thermal Resistance, Junction-case	6	°C/W
$R_{thj-a}$	Maximum Thermal Resistance, Junction-ambient (PCB mount) <sup>3</sup>	62.5	°C/W

**AP10N10K****N-Channel Power MOSFET****Electrical Characteristics@ $T_j=25^\circ C$ (unless otherwise specified)**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	100	-	-	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10V, I_D=5A$	-	-	135	$m\Omega$
		$V_{GS}=4.5V, I_D=3A$	-	-	145	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1	-	3	V
$g_{fs}$	Forward Transconductance	$V_{DS}=10V, I_D=5A$	-	17	-	S
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=80V, V_{GS}=0V$	-	-	25	$\mu A$
$I_{GSS}$	Gate-Source Leakage	$V_{GS}= \pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
$Q_g$	Total Gate Charge	$I_D=5A$	-	11	17.6	nC
$Q_{gs}$	Gate-Source Charge	$V_{DS}=80V$	-	12	-	nC
$Q_{gd}$	Gate-Drain ("Miller") Charge	$V_{GS}=10V$	-	2	-	nC
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=50V$	-	6	-	ns
$t_r$	Rise Time	$I_D=5A$	-	8	-	ns
$t_{d(off)}$	Turn-off Delay Time	$R_G=3.3\Omega$	-	14	-	ns
$t_f$	Fall Time	$V_{GS}=10V$	-	3	-	ns
$C_{iss}$	Input Capacitance	$V_{GS}=0V$	-	580	928	pF
$C_{oss}$	Output Capacitance	$V_{DS}=50V$	-	27	-	pF
$C_{rss}$	Reverse Transfer Capacitance	$f=1.0MHz$	-	19	-	pF
$R_g$	Gate Resistance	$f=1.0MHz$	-	2	4	$\Omega$

**Source-Drain Diode**

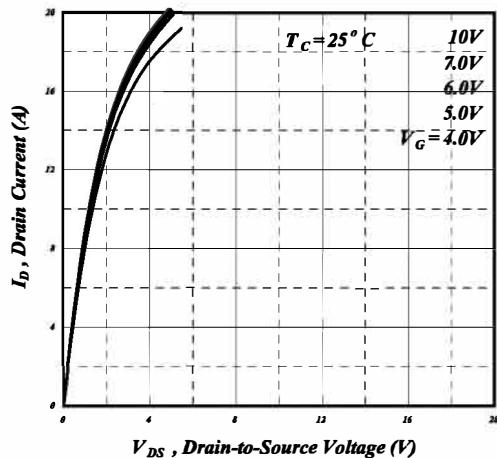
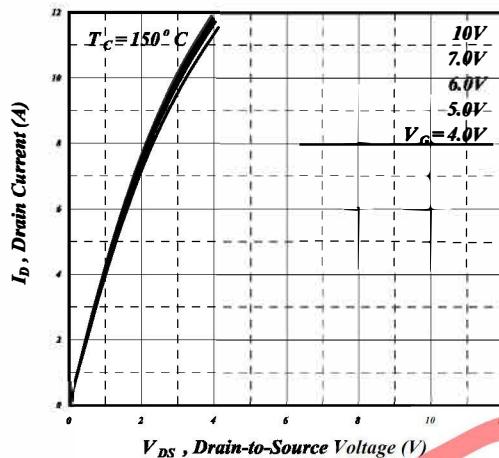
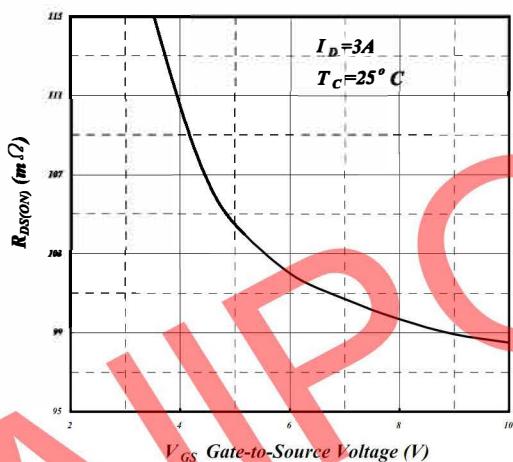
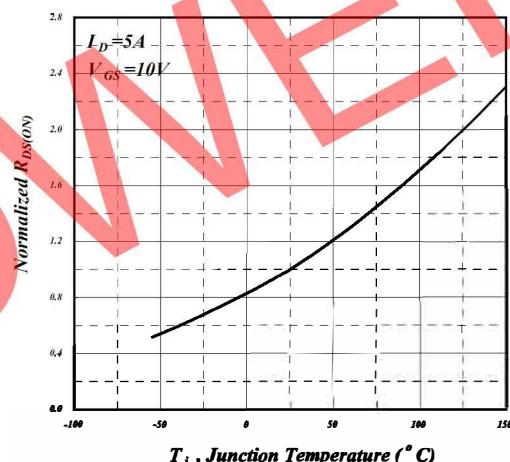
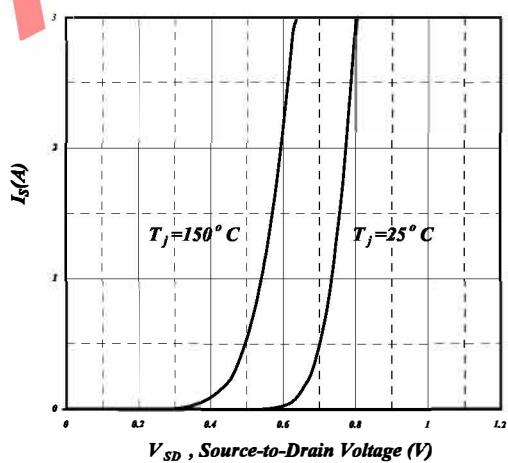
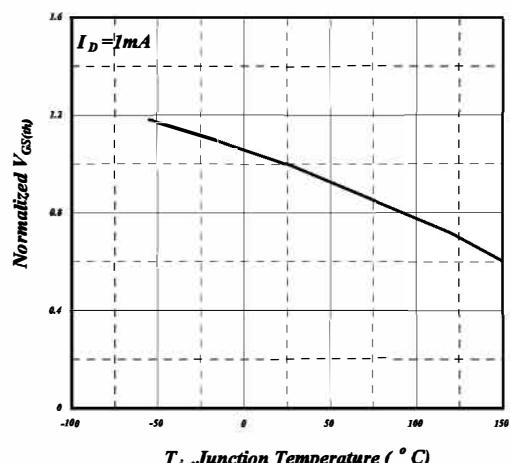
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{SD}$	Forward On Voltage <sup>2</sup>	$I_S=5A, V_{GS}=0V$	-	-	1.3	V
$t_{rr}$	Reverse Recovery Time	$I_S=5A, V_{GS}=0V,$	-	20	-	ns
$Q_{rr}$	Reverse Recovery Charge	$dI/dt=100A/\mu s$	-	18	-	nC

**Notes:**

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse test
- 3.Surface mounted on 1 in<sup>2</sup> copper pad of FR4 board
- 4.Starting  $T_j=25^\circ C$  ,  $V_{DD}=50V$  ,  $L=1mH$  ,  $R_G=25\Omega$

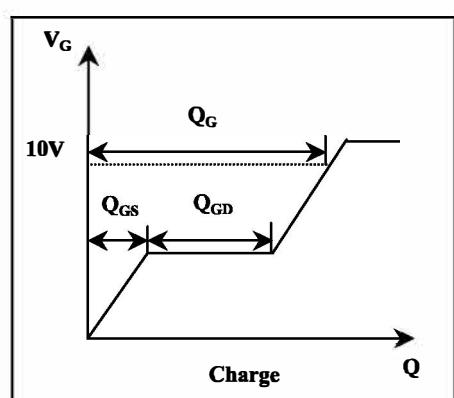
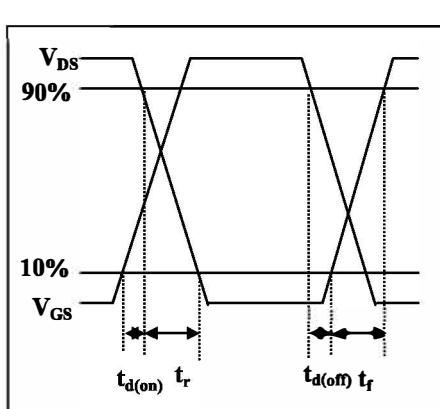
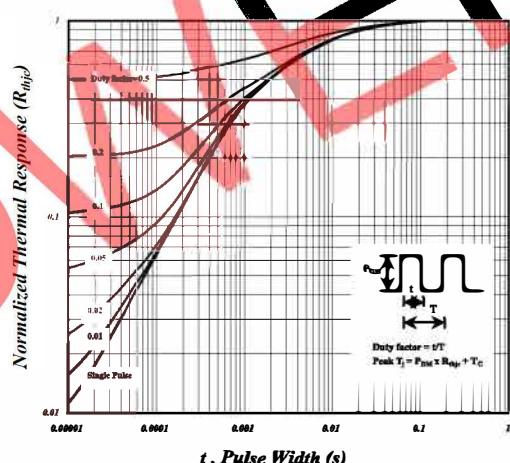
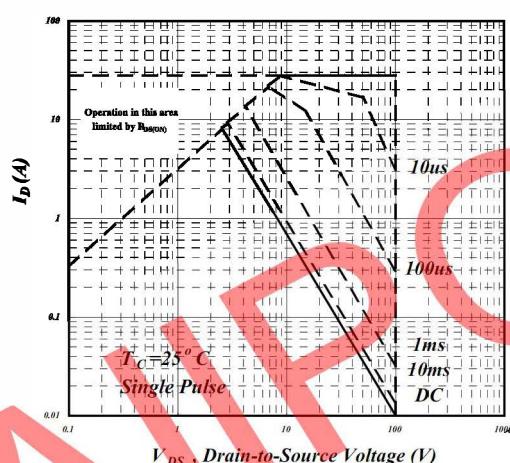
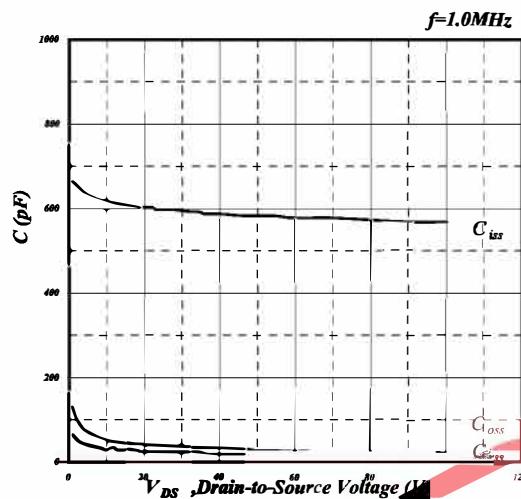
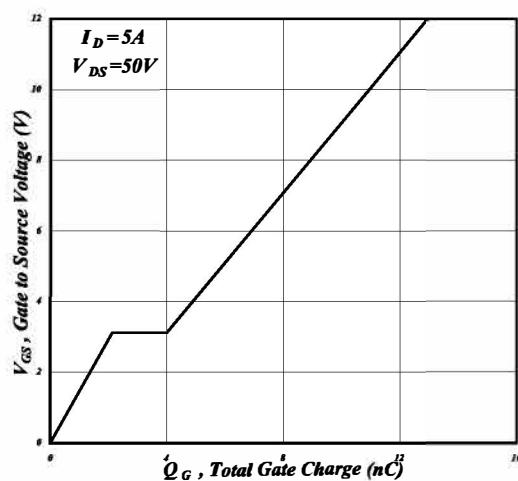
**AP10N10K**

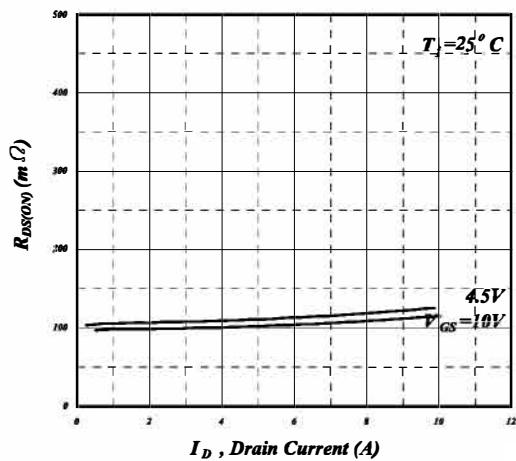
N-Channel Power MOSFET

**Fig 1. Typical Output Characteristics****Fig 2. Typical Output Characteristics****Fig 3. On-Resistance v.s. Gate Voltage****Fig 4. Normalized On-Resistance v.s. Junction Temperature****Fig 5. Forward Characteristic of Reverse Diode****Fig 6. Gate Threshold Voltage v.s. Junction Temperature**

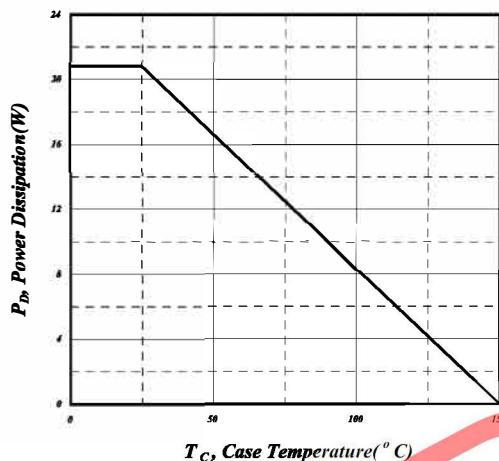
**AP10N10K**

N-Channel Power MOSFET

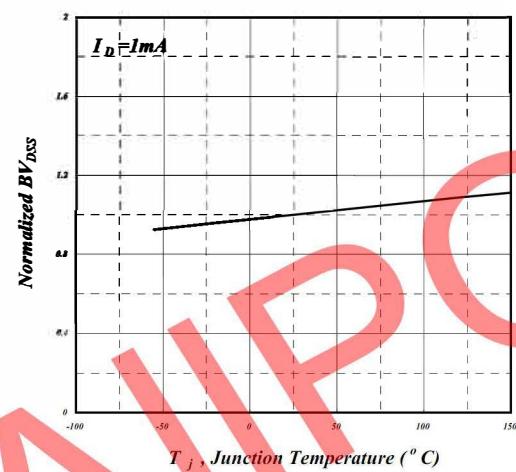


**AP10N10K****N-Channel Power MOSFET**

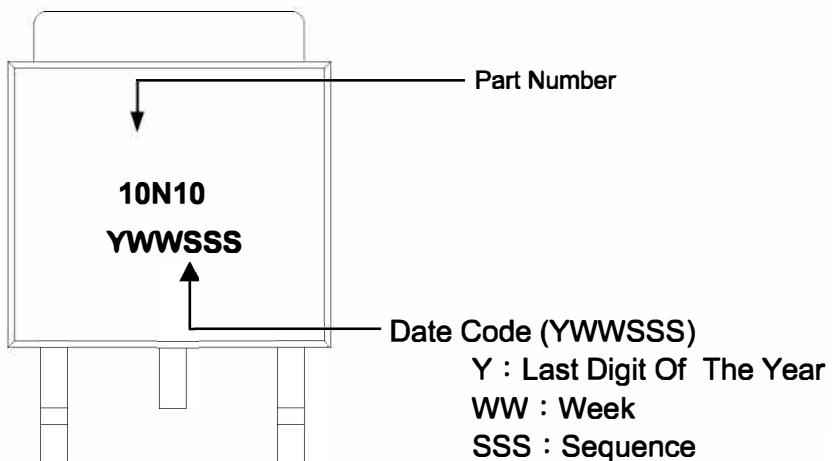
**Fig 13. Typ. Drain-Source on State Resistance**



**Fig 14. Total Power Dissipation**



**Fig 15. Normalized  $BV_{DS(on)}$  v.s. Junction**

**MARKING INFORMATION**

AIPOWER

# X-ON Electronics

Largest Supplier of Electrical and Electronic Components

***Click to view similar products for MOSFET category:***

***Click to view products by Quan Li manufacturer:***

Other Similar products are found below :

[614233C](#) [648584F](#) [MCH3443-TL-E](#) [MCH6422-TL-E](#) [FDPF9N50NZ](#) [FW231A-TL-E](#) [APT5010JVR](#) [NTNS3A92PZT5G](#) [IRF100S201](#)  
[JANTX2N5237](#) [2SK2464-TL-E](#) [2SK3818-DL-E](#) [FCA20N60\\_F109](#) [FDZ595PZ](#) [STD6600NT4G](#) [FSS804-TL-E](#) [2SJ277-DL-E](#) [2SK1691-DL-](#)  
[E](#) [2SK2545\(Q,T\)](#) [D2294UK](#) [405094E](#) [423220D](#) [MCH6646-TL-E](#) [TPCC8103,L1Q\(CM](#) [367-8430-0972-503](#) [VN1206L](#) [424134F](#) [026935X](#)  
[051075F](#) [SBVS138LT1G](#) [614234A](#) [715780A](#) [NTNS3166NZT5G](#) [751625C](#) [873612G](#) [IRF7380TRHR](#) [IPS70R2K0CEAKMA1](#)  
[RJK60S3DPP-E0#T2](#) [RJK60S5DPK-M0#T0](#) [APT5010JVFR](#) [APT12031JFLL](#) [APT12040JVR](#) [DMN3404LQ-7](#) [NTE6400](#) [JANTX2N6796U](#)  
[JANTX2N6784U](#) [JANTXV2N5416U4](#) [SQM110N05-06L-GE3](#) [SIHF35N60E-GE3](#) [2SK2614\(TE16L1,Q\)](#)